

line 3, please cancel "includes multi-alignment" and insert -utilizes a plurality of alignment marks- -;

*a13*

line 4, before "strips" insert - -substrate- -;

line 6, please cancel "alignments" and insert - -alignment marks- -;

line 7, before "strips" insert - -substrate- -;

line 9, please cancel "alignments" and insert "alignment marks- -";

line 10, before "strips" insert - -substrate- -;

*NE* lines 11-12, delete cannot add to the peripheral substrate areas insert ill not accumulate to the subsequent substrate areas in the substrate strip- -.

**IN THE CLAIMS:**

Please cancel Claims 1 to 6 without prejudice or disclaimer and add the following new claims to the application.

*Sub C3*  
*add* - 7. A process for sawing a substrate strip having a plurality of substrate areas by a saw machine, and the process comprising the steps of:

providing a plurality of alignment marks around each individual substrate area on the substrate strip;

providing a plurality of cutting marks around each individual substrate area on the substrate strip;

positioning the saw machine with respect to each individual substrate area in accordance with the alignment marks therearound; and

cutting each individual substrate area on the substrate strip by the saw machine respectively according to cutting tracks defined by the cutting marks.

*Sub B1*  
*any*  
*cancel*

8. The process as claimed in Claim 7, wherein the substrate strip has a longitudinal axial and a lateral axial and the substrate areas are disposed along the longitudinal axial, the saw machine is positioned with respect to the first substrate area according to the alignment marks along the longitudinal axial from one side thereof and cuts the substrate strip according to cutting tracks defined by the cutting marks parallel to the lateral axial, then, the saw machine is positioned with respect to the next substrate area and then cuts the substrate strip, whereby the cutting error resulted from each substrate area will not accumulate to the subsequent substrate areas in the substrate strip.

9. The process as claimed in Claim 8, further comprising the step of cutting the substrate strip according to cutting tracks defined by the cutting marks parallel to the longitudinal axial.

10. The process as claimed in Claim 7, wherein each individual substrate area is provided with at least three alignment marks.

11. The process as claimed in Claim 7, further comprising an encapsulated area on each individual substrate area, and the encapsulated area is provided with at least three alignment marks therearound.

12. The process as claimed in Claim 7, wherein two substrate strips are juxtaposed for cutting simultaneously.--